

# Low Input Current, High Gain Optocouplers

# **Technical Data**

#### **Features**

- High Current Transfer Ratio – 2000% Typical (4500% Typical for HCNW139/138)
- Low Input Current Requirements – 0.5 mA
- TTL Compatible Output 0.1 V V<sub>OL</sub> Typical
- Performance Guaranteed over Temperature 0°C to 70°C
- Base Access Allows Gain Bandwidth Adjustment
- High Output Current 60 mA
- Safety Approval
   UL Recognized 2500 V rms
   for 1 Minute and 5000 V rms\*
   for 1 Minute per UL 1577

   CSA Approved
   VDE 0884 Approved with
   V<sub>IORM</sub> = 1414 V peak for
   HCNW139 and HCNW138

BSI Certified (HCNW139 and HCNW138)

 Available in 8-Pin DIP or SOIC-8 Footprint or Widebody Package

• MIL-STD-1772 Version Available (HCPL-5700/1)

#### Applications

- Ground Isolate Most Logic Families – TTL/TTL, CMOS/ TTL, CMOS/CMOS, LSTTL/ TTL, CMOS/LSTTL
- Low Input Current Line Receiver
- High Voltage Insulation (HCNW139/138)
- EIA RS-232C Line Receiver
- Telephone Ring Detector
- 117 V ac Line Voltage Status Indicator – Low Input Power Dissipation
- Low Power Systems Ground Isolation

#### **Functional Diagram**

6N139	6N138
HCPL-0701	HCPL-0700
HCNW139	HCNW138

#### Description

These high gain series couplers use a Light Emitting Diode and an integrated high gain photodetector to provide extremely high current transfer ratio between input and output. Separate pins for the photodiode and output stage result in TTL compatible saturation voltages and high speed operation. Where desired the  $V_{CC}$  and  $V_{O}$  terminals may be tied together to achieve conventional photodarlington operation. A base access terminal allows a gain bandwidth adjustment to be made.



\*5000 V rms/1 minute rating is for HCNW139/138 and Option 020 (6N139/138) products only. A 0.1  $\mu F$  bypass capacitor connected between pins 8 and 5 is recommended.

CAUTION: It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD.

The 6N139, HCPL-0701, and CNW139 are for use in CMOS, LSTTL or other low power applications. A 400% minimum current transfer ratio is guaranteed over 0 to 70°C operating range for only 0.5 mA of LED current.

The 6N138, HCPL-0700, and HCNW138 are designed for use mainly in TTL applications. Current Transfer Ratio (CTR) is 300% minimum over 0 to 70°C for an LED current of 1.6 mA (1 TTL Unit load ). A 300% minimum CTR enables operation with 1 TTL Load using a 2.2  $k\Omega$  pull-up resistor.

Selection for lower input current down to 250  $\mu A$  is available upon request.

The HCPL-0701 and HCPL-0700 are surface mount devices packaged in an industry standard SOIC-8 footprint. The SOIC-8 does not require "through holes" in a PCB. This package occupies approximately one-third the footprint area of the standard dual-in-line package. The lead profile is designed to be compatible with standard surface mount processes.

The HCNW139 and HCNW138 are packaged in a widebody encapsulation that provides creepage and clearance dimensions suitable for safety approval by regulatory agencies worldwide.

#### **Selection Guide**

8-Pin I (300 M		Small Outline SO-8		Widebody       Package       Small Outline SO-8     (400 mil)						Hermetic Single and
Single Channel Package	Dual Channel Package HCPL-	Single Channel Package HCPL-	Dual Channel Package HCPL-	Single Channel Package	Minimum Input ON Current (I <sub>F</sub> )	Minimum CTR	Absolute Maxi- mum V <sub>CC</sub>	Dual Channel Packages HCPL-		
6N139	2731 <sup>[1]</sup>	0701	0731	HCNW139	0.5 mA	400%	18 V			
6N138	2730 <sup>[1]</sup>	0700	0730	HCNW138	1.6 mA	300%	7 V			
HCPL-4701 <sup>[1]</sup>	4731[1]	070A <sup>[1]</sup>	073A <sup>[1]</sup>		40 µA	800%	18 V			
					0.5 mA	300%	20 V	5701 <sup>[1]</sup> 5700 <sup>[1]</sup> 5731 <sup>[1]</sup> 5730 <sup>[1]</sup>		

#### Note:

1. Technical data are on separate HP publications.

## **Ordering Information**

Specify Part Number followed by Option Number (if desired).

Example:

6N139#XXX 020 = 5000 V rms/1 Minute UL Rating Option\* 300 = Gull Wing Surface Mount Option† 500 = Tape and Reel Packaging Option

Option data sheets available. Contact your Hewlett-Packard sales representative or authorized distributor for information.

\*For 6N139 and 6N138 only.

†Gull wing surface mount option applies to through hole parts only.

#### Schematic



## Package Outline Drawings

8-Pin DIP Package (6N139/6N138)\*\*



8-Pin DIP Package with Gull Wing Surface Mount Option 300 (6N139/6N138)





#### Small Outline SO-8 Package (HCPL-0701/HCPL-0700)

8-Pin Widebody DIP Package (HCNW139/HCNW138)





#### 8-Pin Widebody DIP Package with Gull Wing Surface Mount Option 300 (HCNW139/HCNW138)

Solder Reflow Temperature Profile (HCPL-07XX and Gull Wing Surface Mount Option 300 Parts)



Note: Use of nonchlorine activated fluxes is highly recommended.

#### **Regulatory Information**

The 6N139/138, HCNW139/138, and HCPL-0701/0700 have been approved by the following organizations:

#### UL

Recognized under UL 1577, Component Recognition Program, File E55361.

#### CSA

Approved under CSA Component Acceptance Notice #5, File CA 88324.

#### VDE

Approved according to VDE 0884/ 06.92 (HCNW139/138 only).

## BSI

Certification according to BS415:1994, (BS EN60065:1994); BS EN60950:1992 (BS7002:1992) and EN41003:1993 for Class II applications (HCNW139/ HCNW138 only.)

Parameter	Symbol	8-Pin DIP (300 Mil) Value	SO-8 Value	Widebody (400 Mil) Value	Units	Conditions
Minimum External Air Gap (External Clearance)	L(101)	7.1	4.9	9.6	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (External Creepage)	L(102)	7.4	4.8	10.0	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	0.08	1.0	mm	Through insulation distance, conductor to conductor, usually the direct distance between the photoemitter and photodetector inside the optocoupler cavity.
Minimum Internal Tracking (Internal Creepage)		NA	NA	4.0	mm	Measured from input terminals to output terminals, along internal cavity.
Tracking Resistance (Comparative Tracking Index)	CTI	200	200	200	Volts	DIN IEC 112/VDE 0303 Part 1
Isolation Group		IIIa	IIIa	IIIa		Material Group (DIN VDE 0110, 1/89, Table 1)

## **Insulation and Safety Related Specifications**

Option 300 - surface mount classification is Class A in accordance with CECC 00802.

Description	Symbol	Characteristic	Units
Installation Classification per DIN VDE 0110/1.89, Table 1 for rated mains voltage $\leq 600$ V rms		I-IV	
for rated mains voltage $\leq 1000$ V rms		I-III	
Climatic Classification		55/100/21	
Pollution Degree (DIN VDE 0110/1.89)		2	
Maximum Working Insulation Voltage	V <sub>IORM</sub>	1414	V peak
Input to Output Test Voltage, Method b* $V_{PR} = 1.875 \text{ x } V_{IORM}, 100\%$ Production Test with $t_P = 1$ sec, Partial Discharge < 5 pC	V <sub>PR</sub>	2652	V peak
Input to Output Test Voltage, Method a* $V_{PR} = 1.5 \text{ x } V_{IORM}$ , Type and Sample Test, $t_P = 60 \text{ sec}$ , Partial Discharge < 5 pC	V <sub>PR</sub>	2121	V peak
Highest Allowable Overvoltage* (Transient Overvoltage, t <sub>ini</sub> = 10 sec)	V <sub>IOTM</sub>	8000	V peak
Safety Limiting Values (Maximum values allowed in the event of a failure, also see Figure 11, Thermal Derating curve.)			
Case Temperature	$T_{S}$	175	°C
Current (Input Current $I_F$ , $P_S = 0$ )	I <sub>S,INPUT</sub>	400	mA
Output Power	P <sub>S,OUTPUT</sub>	700	mW
Insulation Resistance at $T_S$ , $V_{IO} = 500 \text{ V}$	R <sub>S</sub>	$> 10^9$	Ω

VDE 0884 Insulation Related Characteristics (HCNW139 and HCNW138)

\*Refer to the front of the optocoupler section of the current catalog, under Product Safety Regulations section, (VDE 0884) for a detailed description.

Note: Isolation characteristics are guaranteed only within the safety maximum ratings which must be ensured by protective circuits in application.

Parameter	arameter Symbol Min. Max.					
Storage Temperature		T <sub>s</sub>	-55	125	°C	
Operating Temperature**		T <sub>A</sub>	-40	85	°C	
Average Forward Input Current		20	mA			
Peak Forward Input Current (50% Duty Cycle, 1 ms Pulse Wid	th)	I <sub>F(AVG)</sub> I <sub>FPK</sub>		40	mA	
Peak Transient Input Current (<1 μs Pulse Width, 300 pps)		I <sub>F(TRAN)</sub>		1.0	A	
Reverse Input Voltage	V <sub>R</sub>		5	V		
	HCNW139/138			3	V	
Input Power Dissipation		PI		35	mW	
Output Current (Pin 6)	Output Current (Pin 6)				mA	
Emitter Base Reverse Voltage (Pin	5-7)	V <sub>EB</sub>		0.5	V	
Supply Voltage and Output Voltage (6N139, HCPL-0701, HCNW139)		V <sub>CC</sub>	-0.5	18	V	
Supply Voltage and Output Voltage (6N138, HCPL-0700, HCNW138)		V <sub>CC</sub>	-0.5	7	V	
Output Power Dissipation		Po		100	mW	
Total Power Dissipation		P <sub>T</sub>		135	mW	
Lead Solder Temperature (for Thro	ugh Hole Devices)	260℃ for 10	sec., 1.6 mi	n below seat	ing plane	
	HCNW139/138	260°C for 10 sec., up to seating plane				
Reflow Temperature Profile (for SOIC-8 and Option #300)		See Package Outline Drawings section				

Absolute Maximum Ratings\* (No Derating Required up to 85°C)

\*JEDEC Registered Data for 6N139 and 6N138. \*\*0°C to 70°C on JEDEC Registration.

# **Recommended Operating Conditions**

Parameter	Symbol	Min.	Max.	Units
Power Supply Voltage	V <sub>CC</sub>	4.5	18	V
Forward Input Current (ON)	I <sub>F(ON)</sub>	0.5	12.0	mA
Forward Input Voltage (OFF)	V <sub>F(OFF)</sub>	0	0.8	V
Operating Temperature	T <sub>A</sub>	0	70	°C

## **Electrical Specifications**

 $0^{\circ}C \leq T_A \leq 70^{\circ}C$ ,  $4.5 \text{ V} \leq V_{CC} \leq 18 \text{ V}$ ,  $0.5 \text{ mA} \leq I_{F(ON)} \leq 12 \text{ mA}$ ,  $0 \text{ V} \leq V_{F(OFF)} \leq 0.8 \text{ V}$ , unless otherwise specified. All Typicals at  $T_A = 25^{\circ}C$ . See Note 7.

Parameter	Sym.	Device		Typ.**			Test Cond		Fig.	Note
Current Transfer Ratio	CTR	6N139 HCPL-0701	400*	2000	5000	%	$I_F = 0.5 \text{ mA}$	$V_{\rm CC} = 4.5$ $V_{\rm O} = 0.4$ V	2,3	1, 2, 4
		HCNW139	400	4500				1		
		6N139 HCPL-0701	500*	1600	2600		$I_F = 1.6 \text{ mA}$			
		HCNW139	500	3000						
			300	1600			$I_{\rm F} = 5.0  {\rm mA}$	]		
			200	850			$I_F = 12 \text{ mA}$	-		
		6N138 HCPL-0700	300*	1600	2600		$I_F = 1.6 \text{ mA}$			
		HCNW138		1500						
Logic Low Output Voltage	V <sub>OL</sub>	6N139 HCPL-0701 HCNW139		0.1	0.4	V	$I_{\rm F} = 0.5 \text{ mA},$ $I_{\rm O} = 2 \text{ mA}$	$V_{\rm CC} = 4.5$	1	2
							$I_{\rm F} = 1.6  {\rm mA},$	Ī		
							$I_0 = 8 \text{ mA}$	ļ		
							$I_{\rm F} = 5.0 \text{ mA},$ $I_{\rm O} = 15 \text{ mA}$			
				0.2			$I_F = 12 \text{ mA},$ $I_O = 24 \text{ mA}$			
		6N138	Ť	0.1	1		$I_{\rm F} = 1.6  {\rm mA},$	Ī		
		HCPL-0700 HCNW138					$I_0 = 4.8 \text{ mA}$			
Logic High Output Current	I <sub>OH</sub>	6N139 HCPL-0701 HCNW139		0.05	100	μA	$V_{\rm O} = V_{\rm CC} = 18 \text{ V}$	$I_F = 0 mA$		2
		6N138 HCPL-0700 HCNW138		0.1	250	-	$V_O = V_{CC} = 7 V$			
Logic Low Supply Current	I <sub>CCL</sub>	6N138/139 HCPL-0701/ 0700		0.4	1.5	mA	$I_{\rm F} = 1.6 \text{ mA}, V_0$ $V_{\rm CC} = 18 \text{ V}$	= Open,	10	2
		HCNW139 HCNW138		0.5	2					
Logic High Supply Current	I <sub>CCH</sub>	6N138/139 HCPL-0701/ 0700		0.01	10	μA	$I_{\rm F} = 0 \text{ mA}, V_{\rm O} = V_{\rm CC} = 18 \text{ V}$	· Open,		2
		HCNW139 HCNW138			1	-				
Input Forward Voltage	V <sub>F</sub>	6N138 6N139	1.25	1.40	1.7*	V	$T_A = 25^{\circ}C$ $I_F =$	= 1.6 mA	4,8	
voltage		HCPL-0701 HCPL-0700			1.75	-				
		HCNW139	1.0	1.45	1.85	1	$T_A = 25^{\circ}C$			
		HCNW138	110				-A -0 0			
			0.95		1.95					
Input Reverse Breakdown	BVR		5.0*			V	$I_{\rm R} = 10 \mu\text{A}, T_{\rm A} = I_{\rm R} = 100 \mu\text{A}, T_{\rm A}$	= 25°C		
Voltage		HCNW139 HCNW138	3.0					= 25°C		
Temperature Coefficient of Forward Voltage	$\frac{\Delta V_{\rm F}}{\Delta T_{\rm A}}$			-1.8		mV/°C	$I_F = 1.6 \text{ mA}$		8	
Input	CIN			60		pF	$f = 1 MHz, V_F =$	= 0 V		
Capacitance		HCNW139 HCNW138		90						

\*JEDEC Registered Data for 6N139 and 6N138. \*\*All typical values at  $T_A=25\,^\circ\!C$  and  $V_{CC}=5$  V, unless otherwise noted.

# Switching Specifications (AC)

Over recommended operating conditions ( $T_A = 0$  to 70°C),  $V_{CC} = 5$  V, unless otherwise specified.

Parameter	Sym.	Device	Min.	Typ.**	Max.	Units	<b>Test Conditions</b>	Fig.	Note
Propagation Delay	t <sub>PHL</sub>	6N139		5	25*	μs	$T_A = 25^{\circ}C$	5, 6,	2,4
Time to Logic Low at		HCPL-0701			30		$I_{\rm F} = 0.5  {\rm mA},$	7, 9,	
Output		HCNW139					$Rl = 4.7 k\Omega$	12	
		6N139		0.2	1*	$\mu s$	$T_A = 25^{\circ}C$	1	
		HCPL-0701			2		$I_{\rm F} = 12  {\rm mA},$		
							$Rl = 270 \Omega$		
		HCNW139			1.1				
		6N138		1.6	10*	$\mu s$	$T_A = 25^{\circ}C$	-	
		HCPL-0700					$I_{\rm F} = 1.6  {\rm mA},$		
		HCNW138			15		$Rl = 2.2 k\Omega$		
		HCNW138			11				
Propagation Delay	t <sub>PLH</sub>	6N139		18	60*	μs	$T_A = 25^{\circ}C$	5, 6,	2,4
Time to Logic High		HCPL-0701			90		$I_{\rm F} = 0.5  {\rm mA},$	7, 9,	
at Output		HCNW139					$Rl = 4.7 k\Omega$	12	
		HCNW139			115				
		6N139		2	7*	$\mu s$	$T_A = 25^{\circ}C$		
		HCPL-0701			10		$I_{\rm F} = 12  {\rm mA},$		
		HCNW139					$Rl = 270 \Omega$		
		HCNW139			1.1				
		6N138		10	35*	μs	$T_A = 25^{\circ}C$	1	
		HCPL-0700					$I_{\rm F} = 1.6  {\rm mA},$		
		HCNW138					$Rl = 2.2 k\Omega$		
		6N138			50				
		HCPL-0700							
		HCNW139			70				
Common Mode	CM <sub>H</sub>		1000	10000		V/µs	$I_F = 0 mA,$	13	5, 6
Transient Immunity							$T_A = 25^{\circ}C$		
at Logic High Output							$Rl = 2.2 k\Omega$		
							$ V_{CM}  = 10 V_{P-P}$		
Common Mode	CM <sub>L</sub>		1000	10000		V/µs	$I_{\rm F} = 1.6  {\rm mA},$	13	5, 6
Transient Immunity							$T_A = 25^{\circ}C$		
at Logic Low Output							$Rl = 2.2 k\Omega$		
							$ V_{CM}  = 10 V_{P-P}$		

\*JEDEC Registered Data for 6N139 and 6N138. \*\*All typical values at  $T_A$  = 25  $^{\circ}C$  and  $V_{CC}$  = 5 V, unless otherwise noted.

#### **Package Characteristics**

Para	Parameter		Min.	Typ.**	Max.	Units	Test Conditions	Fig.	Note
Input-Output	Momentary	V <sub>ISO</sub>	2500			V rms	RH < 50%, t = 1 min.,		3, 8
Withstand Vo	Withstand Voltage†						$T_A = 25$ °C		
	Option 020		5000						3, 9
	HCNW139								
	HCNW138								
Resistance (I	Resistance (Input-Output)			1012		Ω	$V_{I-O} = 500  Vdc$		3
							RH < 45%		
Capacitance	(Input-Output)	C <sub>I-O</sub>		0.6		pF	f = 1 MHz		3

\*\*All typicals at  $T_A = 25$  °C, unless otherwise noted.

<sup>†</sup>The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating. For the continuous voltage rating refer to the VDE 0884 Insulation Characteristics Table (if applicable), your equipment level safety specification or HP Application Note 1074 entitled "Optocoupler Input-Output Endurance Voltage."

#### Notes:

- 1. DC CURRENT TRANSFER RATIO (CTR) is defined as the ratio of output collector current,  $I_0$ , to the forward LED input current,  $I_F$ , times 100%.
- 2. Pin 7 Open.
- 3. Device considered a two-terminal device. Pins 1, 2, 3, and 4 shorted together and Pins 5, 6, 7, and 8 shorted together.
- 4. Use of a resistor between pin 5 and 7 will decrease gain and delay time. Significant reduction in overall gain can occur when using resistor values below  $47 \text{ k}\Omega$ . For more information, please contact your local HP Components representative.
- 5. Common mode transient immunity in a Logic High level is the maximum toler-

able (positive)  $dV_{\rm CM}/dt$  of the common mode pulse,  $V_{\rm CM}$ , to assure that the output will remain in a Logic High state (i.e.,  $V_{\rm O} > 2.0$  V). Common mode transient immunity in a Logic Low level is the maximum tolerable (negative)  $dV_{\rm CM}/dt$  of the common mode pulse,  $V_{\rm CM}$ , to assure that the output will remain in a Logic Low state (i.e.,  $V_{\rm O} < 0.8$  V).

- 6. In applications where dV/dt may exceed 50,000 V/µs (such as static discharge) a series resistor,  $\rm R_{CC}$ , should be included to protect the detector IC from destructively high surge currents. The recommended value is  $\rm R_{CC}=220~\Omega.$
- 7. Use of a 0.1  $\mu$ F bypass capacitor connected between pins 8 and 5 adjacent to the device is recommended.
- 8. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage 3000 V rms for 1 second (leakage detection current limit,  $I_{\rm LO} < 5 \ \mu$ A). This test is performed before the 100% production test shown in the VDE 0884 Insulation Related Characteristics Table, if applicable.
- 9. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage > 6000 V rms for 1 second (leakage detection current limit,  $I_{LO} < 5 \ \mu$ A). This test is performed before the 100% production test for partial discharge (method b) shown in the VDE 0884 Insulation Related Characteristics Table, if applicable.



Figure 1. 6N138/6N139 DC Transfer

Characteristics.



Figure 2. Current Transfer Ratio vs. Forward Current 6N138/6N139.



IF - INPUT DIODE FORWARD CURRENT - mA

Figure 3. 6N138/6N139 Output Current vs. Input Diode Forward Current.



Figure 4. Input Diode Forward Current vs. Forward Voltage.



Figure 5. Propagation Delay vs. Temperature.



Figure 6. Propagation Delay vs. Temperature.



Figure 7. Propagation Delay vs. Temperature.



Figure 8. Forward Voltage vs. Temperature.



Figure 9. Nonsaturated Rise and Fall Times vs. Load Resistance.





Figure 10. Logic Low Supply Current vs. Forward Current.

Figure 11. Thermal Derating Curve, Dependence of Safety Limiting Value with Case Temperature per VDE 0884.





Figure 12. Switching Test Circuit.



Figure 13. Test Circuit for Transient Immunity and Typical Waveforms.



www.hp.com/go/isolator

For technical assistance or the location of your nearest Hewlett-Packard sales office, distributor or representative call:

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